

## 1200V N-Channel MOSFET

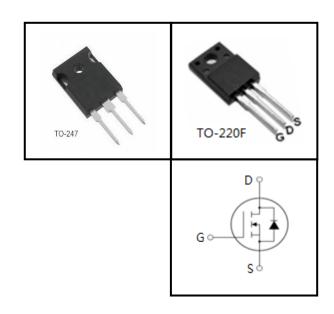
### **FEATURES**

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

### **APPLICATIONS**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

Device Marking and Package Information				
Device Package		Marking		
CS5N120F	TO-220F	CS5N120F		
CS5N120W	TO-247	CS5N120W		



<b>Absolute Maximum Ratings</b> $T_C = 25^{\circ}C$ , unless otherwise noted				
Parameter	Symbol	Value		l l mit
Farameter		TO-220F	TO247	Unit
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>	1200		V
Continuous Drain Current	I <sub>D</sub>	5		А
Pulsed Drain Current (note1)	I <sub>DM</sub>	20		А
Gate-Source Voltage	V <sub>GSS</sub>	±	20	V
Single Pulse Avalanche Energy (note2)	E <sub>AS</sub>	180		mJ
Avalanche Current (note1)	I <sub>AR</sub>	6		А
Repetitive Avalanche Energy (note1)	E <sub>AR</sub>	108		mJ
Power Dissipation (T <sub>C</sub> = 25°C)	P <sub>D</sub>	25	70	W
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+150		°C

Thermal Resistance					
Baramatan	Comple al	Value		1114	
Parameter	Symbol	TO-220F	TO-247	Unit	
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	5	0.78	14/1/1	
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	62.5	60	K/W	



<b>Specifications</b> $T_J = 25^{\circ}C$ , ur	iless othe	rwise noted						
Parameter	Symbol	Test Conditions	Value			Unit		
T di dilloso		Tool Containence	Min.	Тур.	Max.	<b>-</b>		
Static								
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_{D} = 250\mu A$	1200			V		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 1200V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	μA		
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 20V$			±100	nA		
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		5.0	V		
Drain-Source On-Resistance (Note3)	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 2.5A$		2.8	3.4	Ω		
Dynamic								
Input Capacitance	C <sub>iss</sub>	V 0V		1326				
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0V,$ $V_{DS} = 25V,$		122		pF		
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0MHz		20				
Total Gate Charge	$Q_g$			56				
Gate-Source Charge	$Q_{gs}$	$V_{DD} = 960V, I_{D} = 5.0A,$ $V_{GS} = 10V$		6.5		nC		
Gate-Drain Charge	$Q_{gd}$			33.5				
Turn-on Delay Time	t <sub>d(on)</sub>			45				
Turn-on Rise Time	t <sub>r</sub>	$V_{DD} = 600V, I_{D} = 5.0A,$		28				
Turn-off Delay Time	t <sub>d(off)</sub>	$R_G = 25 \Omega$		230		ns		
Turn-off Fall Time	t <sub>f</sub>			49				
Drain-Source Body Diode Character	istics							
Continuous Body Diode Current	Is	T 0500			5			
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> = 25 °C			20	Α		
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25^{\circ}C$ , $I_{SD} = 2.5A$ , $V_{GS} = 0V$			1.4	V		
Reverse Recovery Time	t <sub>rr</sub>	$V_{GS} = 0V, I_{S} = 5.0A,$		711		ns		
Reverse Recovery Charge	Q <sub>rr</sub>	di <sub>F</sub> /dt =100A /μs		1.4		μC		

#### Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L = 10.0mH,  $V_{DD}$  = 50V,  $R_G$  = 25  $\Omega$ , Starting  $T_J$  = 25  $^{\circ}C$
- 3. Pulse Test: Pulse width ≤ 300µs, Duty Cycle ≤ 1%



## **Typical Characteristics** $T_J = 25^{\circ}C$ , unless otherwise noted

Figure 1. Output Characteristics (T<sub>J</sub> = 25°C)

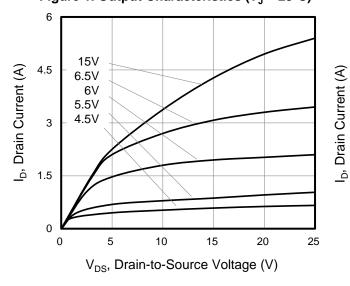


Figure 3. Drain Current vs. Temperature

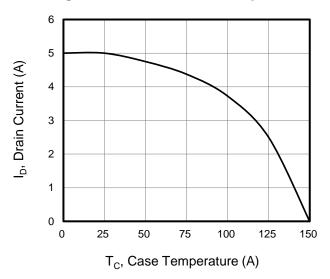


Figure 5. Transfer Characteristics

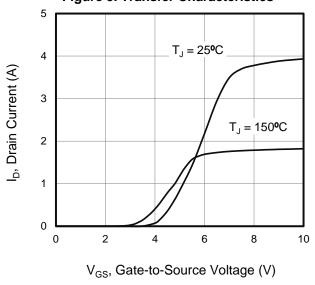


Figure 2. Forward Bias Safe Operating Area

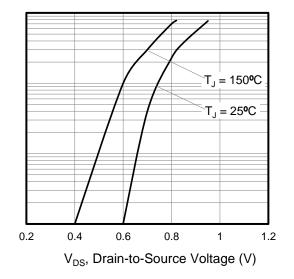


Figure 4. BV<sub>DSS</sub> Variation vs. Temperature

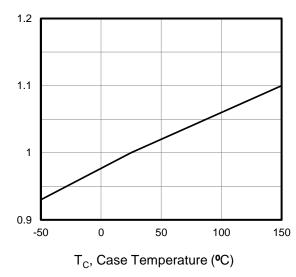
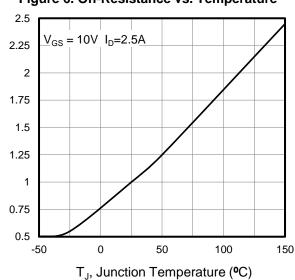


Figure 6. On-Resistance vs. Temperature



 $R_{DS(on)}$ , On-Resistance (Normalized)

BV<sub>DSS</sub> (Normalized)



# **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted



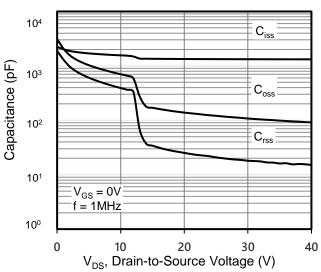


Figure 9. Transient Thermal Impedance TO-220F

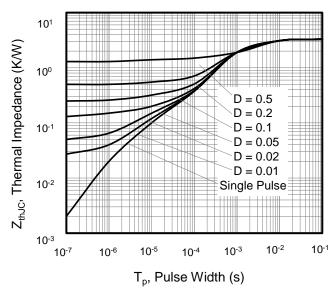
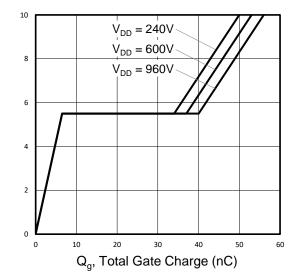


Figure 8. Gate Charge



V<sub>GS</sub>, Gate-to-Source Voltage (V)

Figure 10. Transient Thermal Impedance

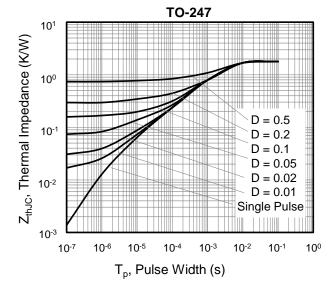




Figure A: Gate Charge Test Circuit and Waveform

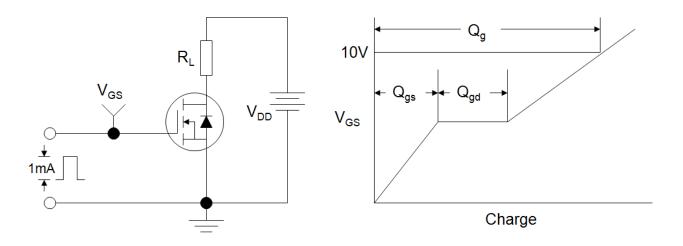


Figure B: Resistive Switching Test Circuit and Waveform

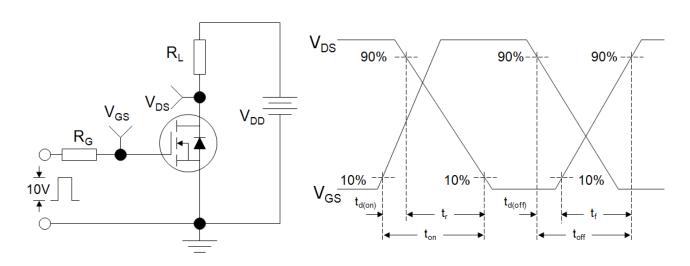
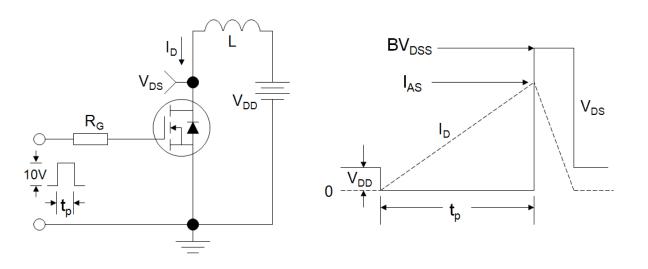
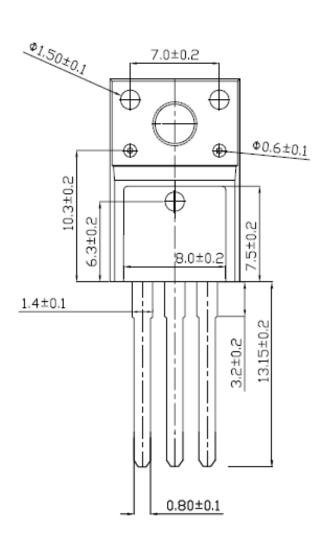


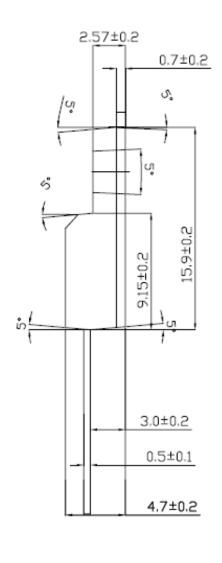
Figure C: Unclamped Inductive Switching Test Circuit and Waveform





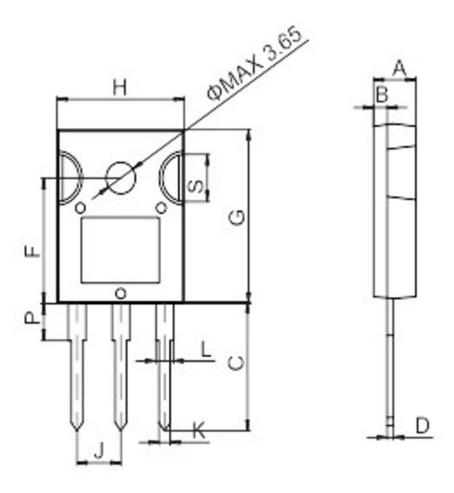
# **TO-220F**







**TO-247** 



Ref.	Dimensions						
	1	MIIImete	rs	Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
А	4.9		5.4	0.193		0.213	
В	1.6		2.0	0.063		0.079	
С	14.35		15.4	0.565		0.606	
D	0.5		0.8	0.020		0.03	
F	14.4		15.1	0.567		0.594	
G	19.7		20.6	0.775		0.81	
Н	15.4		16.2	0.606		0.638	
J	5.3		5.6	0.209		0.220	
K	1.3		1.5	0.051		0.059	
L	2.8		3.3	0.110		0.130	
Р	3.7		4.2	0.146		0.165	
S	5.35		5.65	0.211	\$ ±	0.222	



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